

# IPP45N06S3-16-VB Datasheet N-Channel 60-V (D-S) MOSFET

| PRODUCT             | PRODUCT SUMMARY                  |                                 |  |  |  |
|---------------------|----------------------------------|---------------------------------|--|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}\left(\Omega\right)$  | I <sub>D</sub> (A) <sup>a</sup> |  |  |  |
| 60                  | 0.011 at V <sub>GS</sub> = 10 V  | 60                              |  |  |  |
| 60                  | 0.013 at V <sub>GS</sub> = 4.5 V | 50                              |  |  |  |

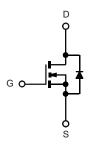
## **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25                   | °C, unless other        | wise noted)                       |                                      |      |  |
|---|-------------------------|-----------------------------------|--------------------------------------|------|--|
| Parameter   |                         | Symbol Limit                      |                                      | Unit |  |
| Gate-Source Voltage   |                         | V <sub>GS</sub>                   | ± 20                                 | V    |  |
| Continuous Prain Current /T = 175 °C\h                          | T <sub>C</sub> = 25 °C  | - I <sub>D</sub>                  | 60                                   |      |  |
| Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup> | T <sub>C</sub> = 100 °C | טי                                | 50ª                                  | ı    |  |
| Pulsed Drain Current  |                         | I <sub>DM</sub>                   | 200                                  | A    |  |
| Continuous Source Current (Diode Conduction)                    |                         | I <sub>S</sub>                    | 50ª                                  |      |  |
| Avalanche Current   |                         | I <sub>AS</sub>                   | 50                                   | 1    |  |
| Single Avalanche Energy (Duty Cycle ≤ 1 %)                      | L = 0.1 mH              | E <sub>AS</sub>                   | 125                                  | mJ   |  |
| Maximum Power Dissipation                                       | T <sub>C</sub> = 25 °C  | P <sub>D</sub>                    | 136                                  | W    |  |
| Maximum Fower Dissipation                                       | T <sub>A</sub> = 25 °C  | ] 'D [                            | 3 <sup>b</sup> , 8.3 <sup>b, c</sup> | "    |  |
| Operating Junction and Storage Temperature Range                | ·                       | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175                          | °C   |  |

| THERMAL RESISTANCE RATINGS               |              |                   |         |         |      |
|--|--------------|-------------------|---------|---------|------|
| Parameter                                |              | Symbol            | Typical | Maximum | Unit |
| Marrian Institut to Amelianda            | t ≤ 10 sec   | R <sub>thJA</sub> | 15      | 18      |      |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State | ↑ ``thJA          | 40      | 50      | °C/W |
| Maximum Junction-to-Case                 |              | R <sub>thJC</sub> | 0.85    | 1.1     |      |

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



| Parameter                                     | Symbol  | Test Conditions   | Min. | Typ.a | Max.  | Unit |  |
|---|---|---|------|-------|-------|------|--|
| Static  |   |   |      |       |       |      |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>   | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$   | 60   |       |       | V    |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>   | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$  | 1    |       | 3     | V    |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>  | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$   |      |       | ± 100 | nA   |  |
|   |   | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V   |      |       | 1     |      |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>  | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C  |      |       | 50    | μΑ   |  |
|   |   | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C  |      |       | 250   |      |  |
| On-State Drain Current <sup>b</sup>           | I <sub>D(on)</sub>  | V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V   | 60   |       |       | Α    |  |
|   |   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A   |      | 0.011 |       |      |  |
|   | D   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C  |      | 0.014 |       | Ω    |  |
| Drain-Source On-State Resistance <sup>b</sup> | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C  |      | 0.018 |       |      |  |
|   |   | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A  |      | 0.013 |       |      |  |
| Forward Transconductance <sup>b</sup>         | 9 <sub>fs</sub>   | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A   |      | 60    |       | S    |  |
| Dynamic                                       |   |   |      |       |       |      |  |
| Input Capacitance                             | C <sub>iss</sub>  |   |      | 4200  |       |      |  |
| Output Capacitance                            | C <sub>oss</sub> V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz |   |      | 570   |       | pF   |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>  |   |      | 325   |       |      |  |
| Total Gate Charge <sup>c</sup>                | Qg  |   |      | 47    |       |      |  |
| Gate-Source Charge <sup>c</sup>               | $Q_{gs}$  | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz  V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A |      | 10    |       | nC   |  |
| Gate-Drain Charge <sup>c</sup>                | $Q_{gd}$  |   |      | 12    |       | 1    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>  |   |      | 10    | 20    |      |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>  | $V_{DD}$ = 30 V, $R_L$ = 0.6 $\Omega$   |      | 15    | 25    | no   |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>   | $I_D \cong 50 \text{ A}, V_{GEN}$ = 10 V, $R_g$ = 2.5 $\Omega$  |      | 35    | 50    | ns   |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>  |   |      | 20    | 30    |      |  |
| Source-Drain Diode Ratings and Cha            | aracteristics (   | T <sub>C</sub> = 25 °C)   |      |       |       |      |  |
| Pulsed Current                                | I <sub>SM</sub>   |   |      |       | 60    | Α    |  |
| Diode Forward Voltage                         | V <sub>SD</sub>   | $I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$  |      | 1     | 1.5   | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>   | I <sub>F</sub> = 20 A, di/dt = 100 A/μs   |      | 45    | 100   | ns   |  |

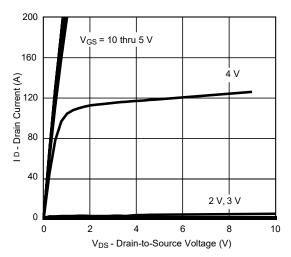
#### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

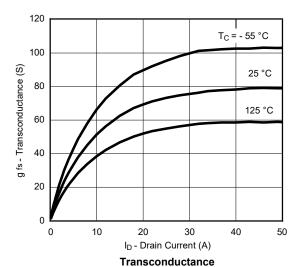
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## TYPICAL CHARACTERISTICS (25 °C unless noted)



### **Output Characteristics**



2- Capacitance (pF) 3000 2400 1800 1300 1200  $\mathsf{C}_{\mathsf{oss}}$ 600  $\mathsf{C}_{\mathsf{rss}}$ 

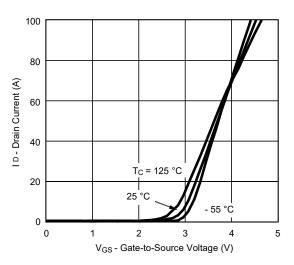
20

C<sub>iss</sub>

V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

30

60



**Transfer Characteristics** 



On-Resistance vs. Drain Current



**Gate Charge** 

4800 4200

3600

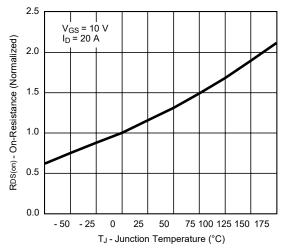
0

0

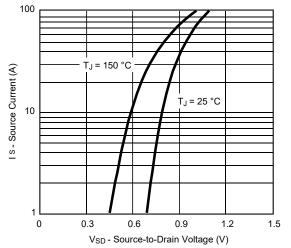
10



## TYPICAL CHARACTERISTICS (25 °C unless noted)



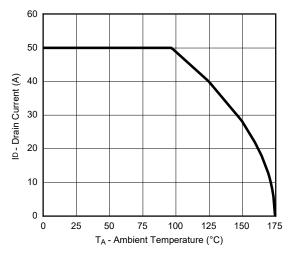
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



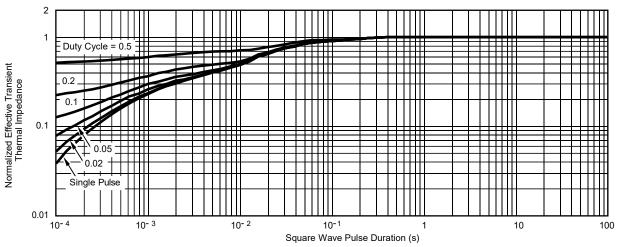
## THERMAL RATINGS



1000 Limited by R<sub>DS(on)\*</sub> 100 100 µs ID - Drain Current (A) 10 1 ms 10 ms 100 ms DC T<sub>C</sub> = 25 °C Single Pulse 0.1 0.01 0.1 10 100  $V_{DS}$  - Drain-to-Source Voltage (V)  $V_{GS}\!>$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area

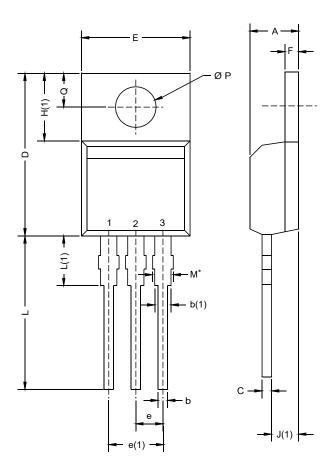
**Maximum Drain Current vs. Ambient Temperature** 



Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-220AB**



| DIM. | MILLIN | IETERS | INCHES |       |  |
|------|--------|--------|--------|-------|--|
|      | MIN.   | MAX.   | MIN.   | MAX.  |  |
| Α    | 4.24   | 4.65   | 0.167  | 0.183 |  |
| b    | 0.69   | 1.02   | 0.027  | 0.040 |  |
| b(1) | 1.14   | 1.78   | 0.045  | 0.070 |  |
| С    | 0.36   | 0.61   | 0.014  | 0.024 |  |
| D    | 14.33  | 15.85  | 0.564  | 0.624 |  |
| E    | 9.96   | 10.52  | 0.392  | 0.414 |  |
| е    | 2.41   | 2.67   | 0.095  | 0.105 |  |
| e(1) | 4.88   | 5.28   | 0.192  | 0.208 |  |
| F    | 1.14   | 1.40   | 0.045  | 0.055 |  |
| H(1) | 6.10   | 6.71   | 0.240  | 0.264 |  |
| J(1) | 2.41   | 2.92   | 0.095  | 0.115 |  |
| L    | 13.36  | 14.40  | 0.526  | 0.567 |  |
| L(1) | 3.33   | 4.04   | 0.131  | 0.159 |  |
| ØΡ   | 3.53   | 3.94   | 0.139  | 0.155 |  |
| Q    | 2.54   | 3.00   | 0.100  | 0.118 |  |

## Note

• M\* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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